# BIOGRAPHY

**Advanced Packaging Summit 2025**

**Name: Choon Lee**
**Title/ Position: SVP/ATTD GM**
**Company: Intel**

- Dec 2023 to present : SVP and ATTD GM at Intel
- Oct 2018 to Nov 2023 : CEO/CTO of JCET and StatsChipPAC
- Mar 2016 to Sep 2018 : VP of Advanced Packaging at Lam Research
- Feb 1996 to Oct 2015 : CTO/Head of BU & Technology/WW Procurement/WW Operation/President of Amkor Korea (Amkor Technology)
- 1993 – 1995 : Post Doc at Korea University
- 1986 – 1993 : MS/Ph.D. at Case Western Reserve Uni.
- 1977- 1983 : BS and MS in physics/statistical physics at Korea univ.